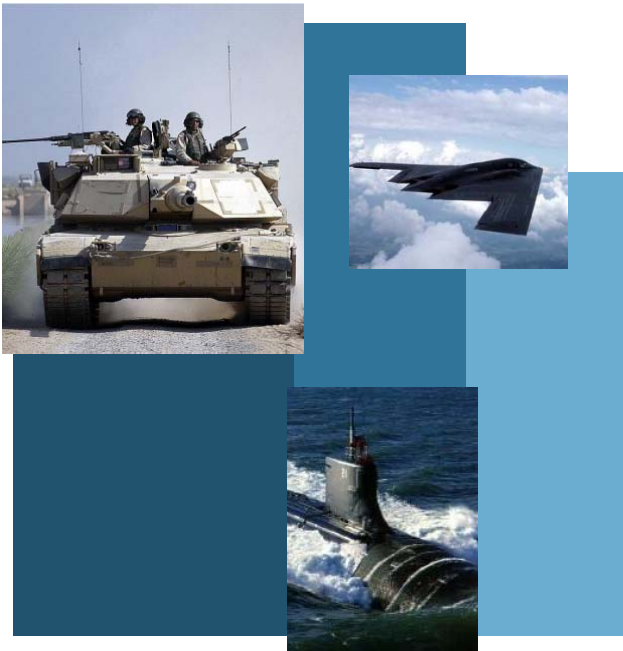


Design Guidelines for Microwave Rigid Flex Circuits



CAPABILITIES

- Single, sequential lamination processes
- Homogeneous and hybrid material multilayers
- Standard plating finishes
- Laser skived access features
- Laser blind vias
- Conductive and non-conductive via fill
- LPI and dry film soldermask types
- Counterbored vias
- Edge plating

DYNACO CORP

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FLEX MATERIALS

- Laminates
 - Rogers R/Flex 3850 Liquid Crystal Polymer
 - Taconic HyRelex TF-270, TF-290 PTFE
- Bond Ply and Cover Material
 - Rogers R/Flex 3908 Liquid Crystal Polymer

RIGID MATERIALS

- Laminates
 - Rogers R/Flex 3850, RO3000, RO4000 series
 - RT/duroid 5000, RT/duroid 6000 series
 - Taconic TLX, TLY, TLC, TLE, RF series
- Bond Ply and Prepreg
 - Rogers R/Flex 3908, RO4400, Taconic Tacpreg/Taclam, FEP, Gore Speedboard C

DESIGN GUIDELINES	
Maximum layer count	20
Smallest mechanically drilled via	.008"
Minimum Annular Ring	.005"
Min line/space width, .5 oz Cu	.003"/.003"
Min line/space width, 1 oz Cu	.005"/.005"
Min line/space width, 2 oz Cu	.008"/.005"
Min external line/space width	.004"/.004"
Minimum Dielectric Thickness	.001"
Minimum Cover Thickness	.001"
Maximum panel size	18" x 24"

Contact Us For More Information!

DyNACO
HIGH RELIABILITY RIGID-FLEX
CIRCUITS & ASSEMBLIES